

## General Description

The VM0102D is a High Power Amplifier MMIC operating in the frequency range from 8 GHz to 11GHz.

The device delivers more than +40dBm saturated output power, and provides 24dB of small signal gain from 8GHz to 11GHz. The design has been optimized to provide high efficiency higher than 40% under +8V supply voltage.

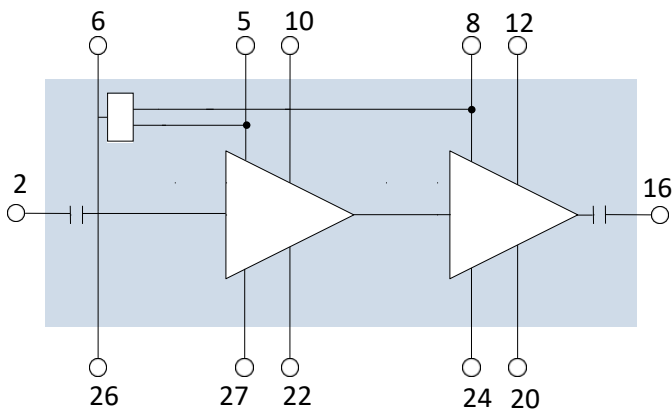
## Features

- Frequency band: 8 to 11GHz
- Output Power (@ Pin=19dBm) > 40dBm
- PAE (@ Pin=19dBm) > 40%
- P1dB > 39dBm
- Small Signal Gain : 24dB
- 50Ω, AC coupled RF input and output access
- Power supply: I<sub>DQ</sub>=2.8A; V<sub>D</sub>= +8V; V<sub>G</sub>= -0.8V
- Chip size: 4.4 x 2.5 x 0.1mm

## Applications

- Radar
- Telecommunications
- Test and measurement

## Pins Assignment & Functional Block Diagram



Symbol	Pad N°
RF in	2
VSS	6/26
VG1	5/27
VD1	10/22
VG2	8/24
VD2	12/20
RF out	16

## Electrical Specifications

Test conditions unless otherwise noted: Post-Layout Simulation

- Tamb.= +25°C
- $V_D = V_{D1} = V_{D2} = +8V$
- $V_G = V_{G1} = V_{G2} = -0.8V$

Symbol	Parameter	Min	Typ	Max	Unit
F	Frequency range	8		11	GHz
BW	Operating Bandwidth		3		GHz
G	Small signal gain		24		dB
Pout	Output power @ Pin= 19 dBm		40		dBm
PAE	Associated Power Added Efficiency @ Pin = 19 dBm		40		%
$I_D$	Supply current total ( $I_D = I_{D1} + I_{D2}$ )		3.2		A
$V_D$	Drain Voltage		8		V
$\Delta G$	Small signal gain flatness		+/- 1.5		dB

## Recommended Operating Conditions

- Post-Layout Simulation

Symbol	Parameter	Values	Unit
$V_D$	Drain voltage	8	V
$V_G$	Gate voltage	-0.8	V

## Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
$V_D$	Drain voltage without RF input		8.5	V
$V_G$	Direct gate bias voltage	-3	0	V
$V_{SS}$	Gate bias voltage	-6	-4	V
$I_D$	Drain bias current ( $I_D = I_{D1} + I_{D2}$ )		4	A
Pin max	RF input power (peak)		+25	dBm

Care should be taken to avoid supply transient and over voltage. Over voltage above the maximum specified in absolute maximum rating section may cause permanent damage to the device.

## Biasing options

### *Biasing access voltage values:*

Pads name	Description	Voltage (V)	Current (A)
$V_{D1}$	First stage drain biasing access	8	$I_D = I_{D1} + I_{D2} = 3.5$
$V_{D2}$	Second stage drain biasing access	8	
$V_{G1}; V_{G2}$	First stage and second stage gates direct biasing access	$-1 < V_G < -0.7$	$I_G = I_{G1} + I_{G2} = 0.1$
$V_{SS}$	First stage and second stage compensated applications dedicated gates biasing access	-5	
Die bottom	DC and RF reference	0	

### *Gate access:*

Depending on the applications environment, the gate of each stage can be biased using one of the three next options:

- Option 1:

Direct gate biasing (each stage individually, use  $V_{G1}$  and  $V_{G2}$ ). This option is dedicated for device characterization period and high level of optimized amplifier functioning point.

- Option 2:

Gate biased using internal circuitry (use  $V_{SS}$ ). This option is dedicated to a dispersion compensation.

### *Drain access:*

The first stage drain can be biased on one side using pad  $V_{D1}$ . The second stage drain must be biased using the two pads  $V_{D2}$  north & south.

### *DC Filtering access:*

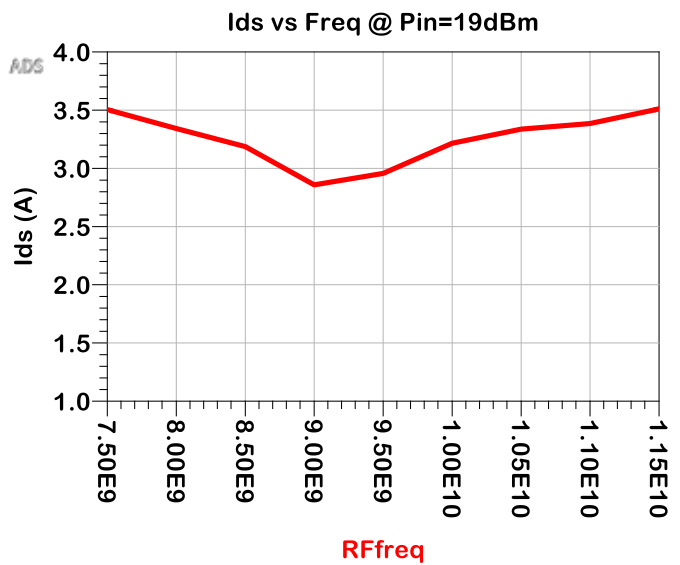
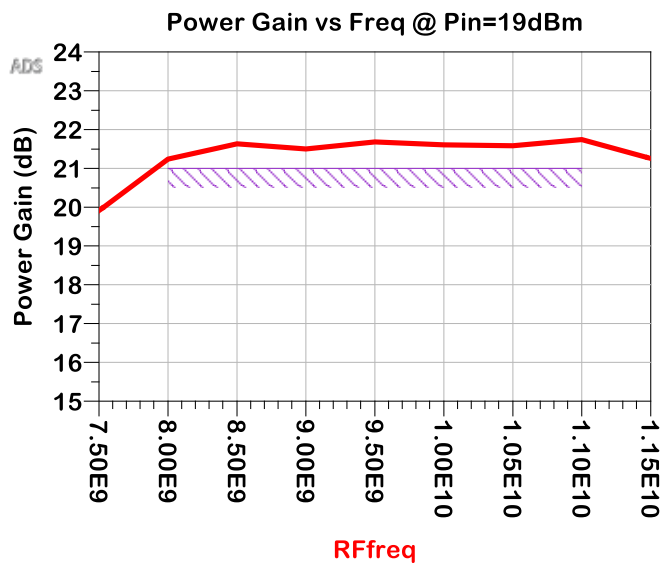
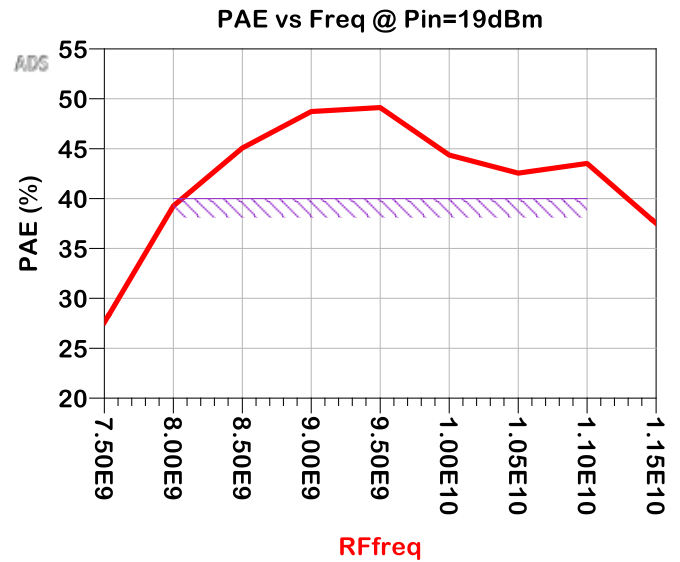
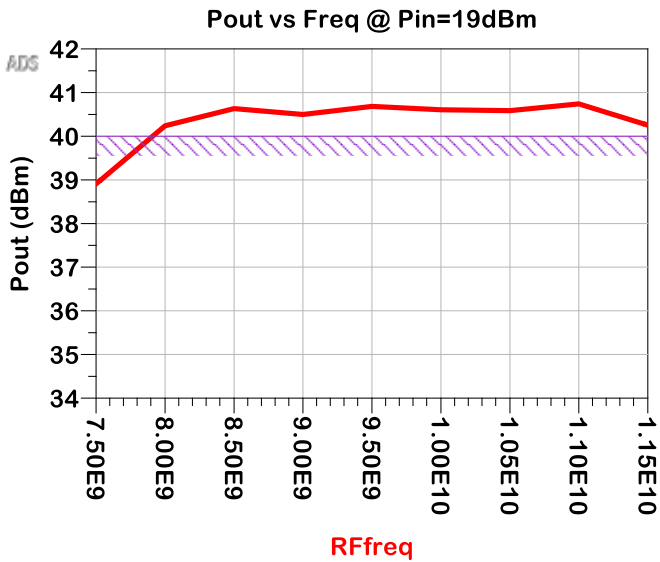
Parallel MIM capacitors must be placed on each used DC pads and on each  $V_{D1}$  access, in order to ensure the amplifier performances. Typically, a 100pF value in D20 format can be used. Also additional 10nF single layer capacitor is recommended on each bias connection.

## Typical Performance (Post-Layout Simulation)

**Bias method: Option 1**

**Test conditions: unless otherwise specified**

- $T_{amb.} = +25^{\circ}\text{C}$
- $V_G = V_{G1} = V_{G2} = -0.8\text{V}$
- $V_D = V_{D1} = V_{D2} = +8\text{V}$
- $I_{DQ} = 2.8\text{A}$

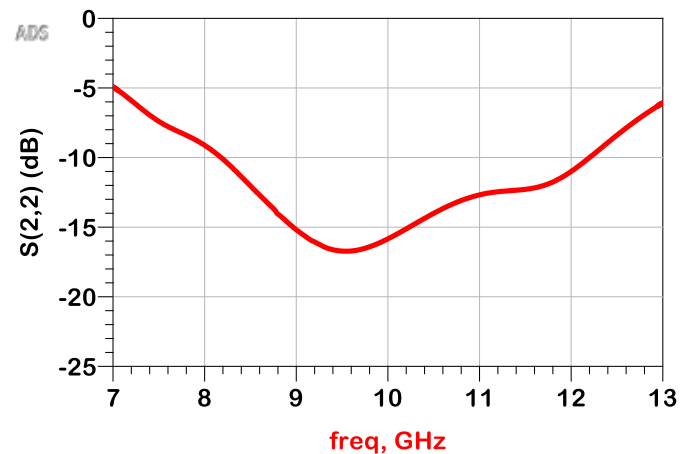
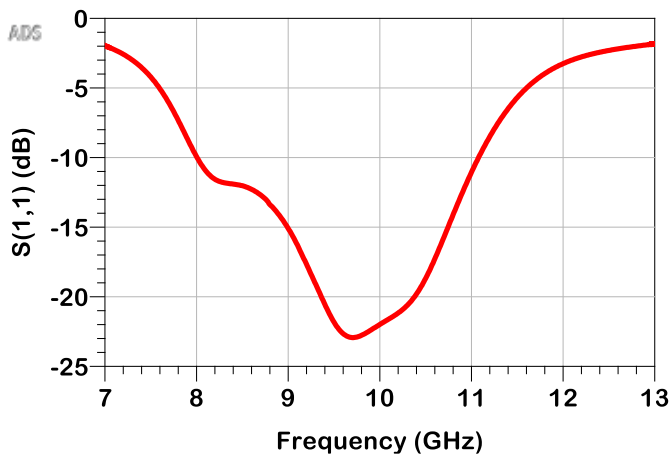
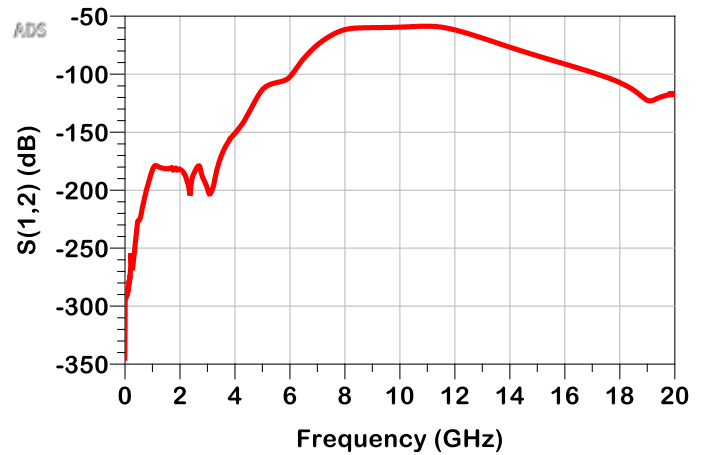
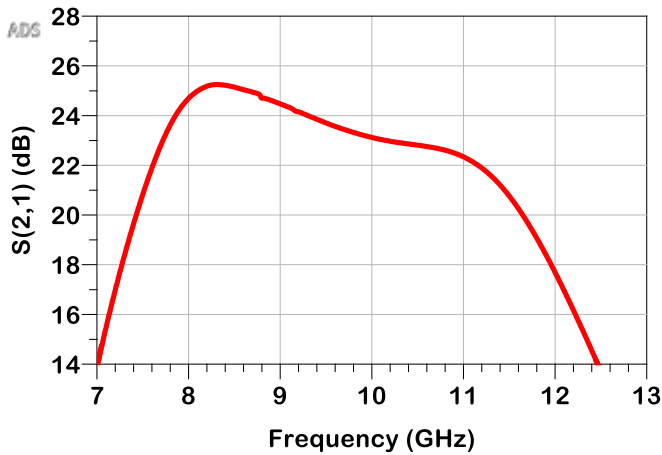


**Typical Performance (Post-Layout Simulation)**

**Option 1**

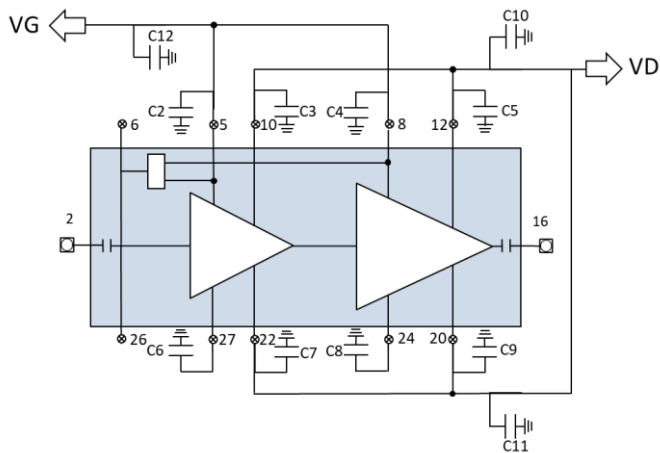
**Test conditions: unless otherwise specified, test under probes**

- $T_{amb.} = +25^{\circ}C$
- $V_D = V_{D1} = V_{D2} = +8V$
- $V_G = V_{G1} = V_{G2} = -0.8V$
- $I_{DQ} = 2.8A$

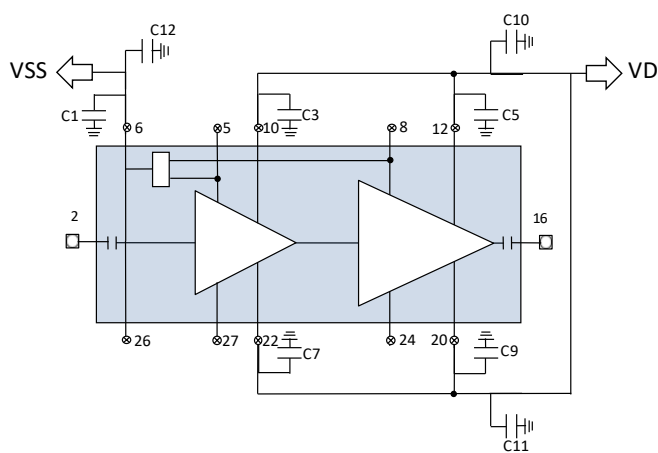


## Application Circuit

- C2 to C9 = 100pF should be MIM capacitor
- C10 to C12 = 10nF

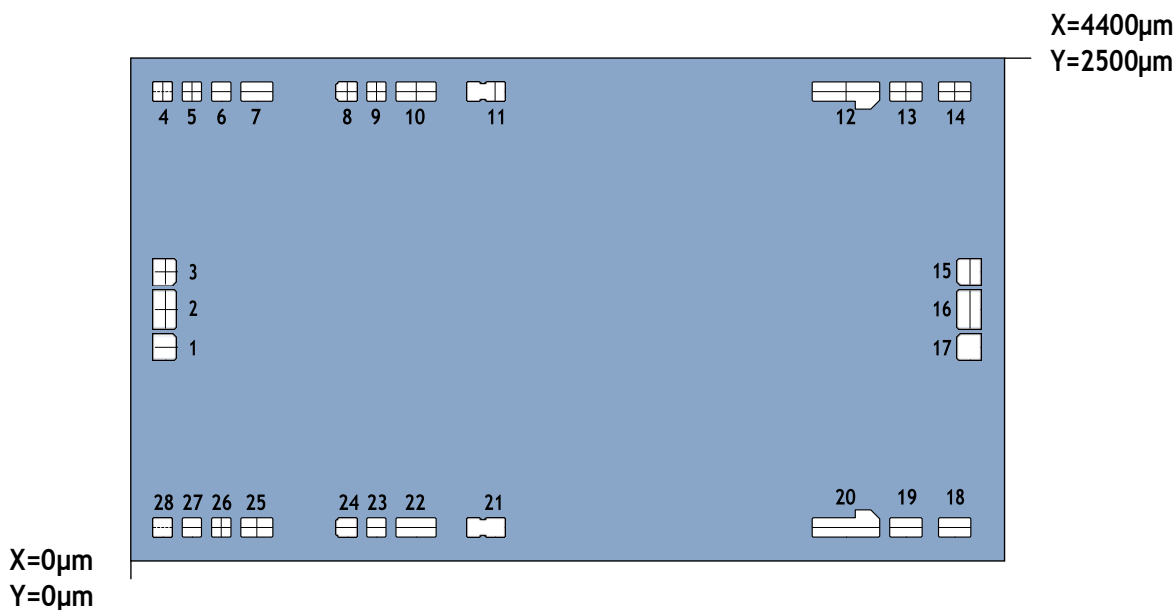


Option1



Option2

## Die Layout



## Pinout and Bonding Pad Coordinates

Die Pin Out				
Pad	X ( $\mu\text{m}$ )	Y ( $\mu\text{m}$ )	Size ( $\mu\text{m} \times \mu\text{m}$ )	Function
1	125	1050	100x100	GND
2	125	1250	100x200	RF_Input : AC Coupled
3	125	1450	100x100	GND
4	125	2368	100x100	N/A
5	275	2368	100x100	V <sub>G1_NORTH</sub>
6	425	2368	100x100	V <sub>SS_NORTH</sub>
7	580	2368	150x100	GND
8	1070	2368	100x100	V <sub>G2_NORTH</sub>
9	1220	2368	100x100	GND
10	1425	2368	200x100	V <sub>D1_NORTH</sub>
11	1825	2368	150x100	GND
12	3570	2368	340x100	V <sub>D2_NORTH</sub>
13	3900	2368	150x100	GND
14	4150	2368	150x100	GND
15	4275	1450	100x100	GND
16	4275	1250	100x200	RF_Output : AC Coupled
17	4275	1050	100x100	GND
18	4150	132	150x100	GND
19	3900	132	150x100	GND
20	3570	132	340x100	V <sub>D2_SOUTH</sub>
21	1825	132	150x100	GND
22	1425	132	200x100	V <sub>D1_SOUTH</sub>
23	1220	132	100x100	GND
24	1070	132	100x100	V <sub>G2_SOUTH</sub>
25	580	132	150x100	GND
26	425	132	100x100	V <sub>SS_SOUTH</sub>
27	275	132	100x100	V <sub>G1_SOUTH</sub>
28	125	132	100x100	N/A

- Die thickness = 100 $\mu\text{m}$
- Die bottom must be connected to ground (RF and DC)

**Ordering Information**

Product Code	Definition
VM0102D	8 to 11 GHz / 10 W

**Associated Material**

Material	Status
Packaged die	Contact factory
Die Evaluation Board (die EVB)	Contact factory
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Mechanical files (DXF)	Contact factory
Measuments files (S2P)	Contact factory

**Product Compliance Information**

**Solderability :**

Use only AuSn (80/20) solder and limit exposure to temperature above 300 °C TO 3 - 4 minutes, maximum

**ESD Sensitiv Rating :**

Test : Human Body Model (HBM)  
 Standard : JEDEC Standard JESD22-A114



**CAUTION ! ESD-Sensitive device**

**RoHS-Compliance :**

This part is compliant with EU 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C15H12Br4O2) Free
- PFOS Free
- SVHC Free

**Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Vectrawave:

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